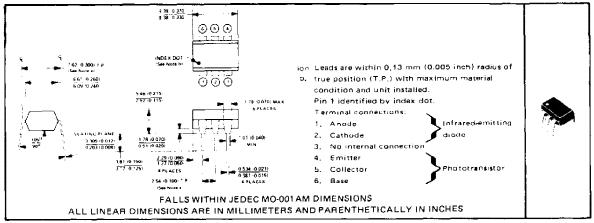
COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Phototransistor
- High Direct-Current Transfer Ratio
- High-Voltage Electrical Isolation . . . 5000-V Rating
- Plastic Dual-In-Line Package
- High-Speed Switching: $t_r = 2 \mu s$, $t_f = 2 \mu s$ Typical
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output Voltage							
Collector-Base Voltage							
Collector-Emitter Voltage (See Note 1)		 		 	-	 	. 30 '
Emitter-Collector Voltage		 	 	 		 	7
Emitter Base Voltage							
Input-Diode Reverse Voltage							
Input-Diode Continuous Forward Current							
Continuous Power Dissipation at (or below) 25°C							
Infrared-Emitting Diode (See Note 2)				 		 	150 m
Phototransistor (See Note 3)							
Total, Infrared-Emitting Diode plus Phototran							
Storage Temperature Range							
	for 10 Seconds						260

NOTES 1. This value applies when the base emitter diode is open-circuited.

- 2. Derate linearly to 100 °C free air temperature at the rate of 2 mW/ °C.
- 3. Denate linearly to 100 $^{\circ}$ C free-air temperature at the rate of 2 mW/ C. .
- 4. Denote linearly to 100 C free-air temperature at the rate of 3.33 mW/ $^{\prime}C_{*}$

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1

TIL124, TIL125, TIL126 Optocouplers

PARAMETER				TIL124			TIL 125			TIL126			[
			TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	ΜΑΧ	UNIT
Collector-Base V(BR)C80 Breakdown Voltage		Ic = 10 µA, IE = 0. IF = 0	70			70			70			v	
VIBR)CEO	Collector Breakdow	-Emitter vn Voltage	l <u>c</u> =1mA, l <u>g</u> ≃0, l _F ≂0	30			30			30			v
Emitter-Base VIBR)EBO Breakdown Voltage		-	$I_{E} = 10 \mu A$, $I_{C} = 0$, $I_{F} = 0$	7			7			7			v
Input Diode Static			VR = 3 V			10			10			10	μA
¹ C(an)	On-State Collector	Phototransistor Operation	VCE = 10 V, IF = 10 mA, IB = 0	1	3		2	5		5	9		mΑ
	Current	Photodiode Operation	V _{CB} = 10 V, I _F = 10 mA, I _E = 0	5	20		5	20		5	20		Αų
^I C(off)	Off-State Collector Current	Phototransistor Operation	V _{CE} = 10 V, I _F ≤ 0 I _B = 0		1	50		1	50		1	50	nA
		Photodiode Operation	V _{CB} = 10 V, i _F = 0, i _E = 0		0.1	20		0.1	20		0.1	20	
Transistor Static NEE Forward Current Transfer Ratio		VCE = 5 V, IC = 10 mA, i⊭ = 0	50	100		100	200		100	550			
V _F F Forward Voltage			IF ≈ 10 mA		1.2	1,4		1.2	1,4		1.2	1.4	v
VCE(sat)	Collector-Emitter E(sat) Saturation Voltage		1 _C = 1 mA, I _F = 10 mA, I _B = 0		0.25	0.4		0,25	0.4		0.25	0.4	v
rio	Input-to-Output Internal Resistance		Vin-out = 500 V, See Note 5	10''			10''			1011			Ω
Cia	Input-to-C	•	Vin-out = 0, f = 1 MHz, See Note 5		1	1.3		1	1.3		1	1.3	pF

electrical characteristics at 25°C free-air temperature

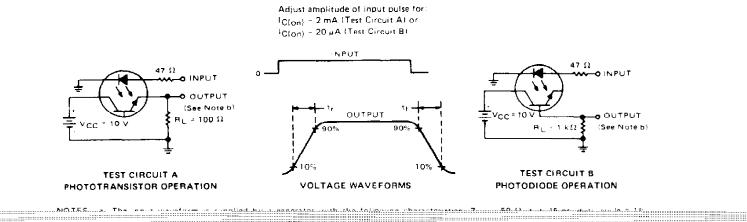
NOTE 5: These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together.

switching characteristics at 25°C free-air temperature

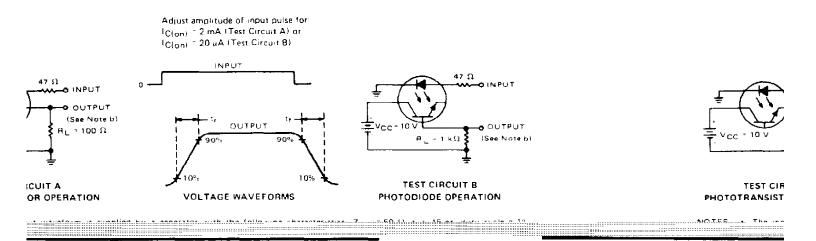
	PARA	METER	TEST CONDITIONS	MIN	TYP	ΜΑΧ	UNIT
t,	Rise Time	Phototransistor	$V_{CC} = 10 V$, $I_{C(on)} = 2 mA_{RL} = 100 \Omega$,		5	10	
ч	Fall Time	Operation	See Test Circuit A of Figure 1		5	10	μs
t _r	Rise Time	Photodiode	$V_{CC} = 10 V$, $I_{C(on)} = 20 \mu A_{RL} = 1 k\Omega$.		1		
t _f	Fall Time	Operation	See Test Circuit B of Figure 1		1		211

TIL124, TIL125, TIL126 **OPTOCOUPLERS**

PARAMETER MEASUREMENT INFORMATION

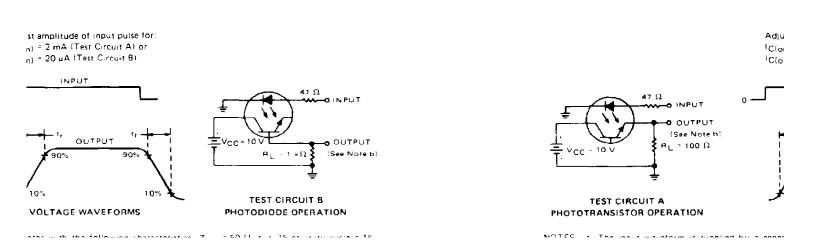




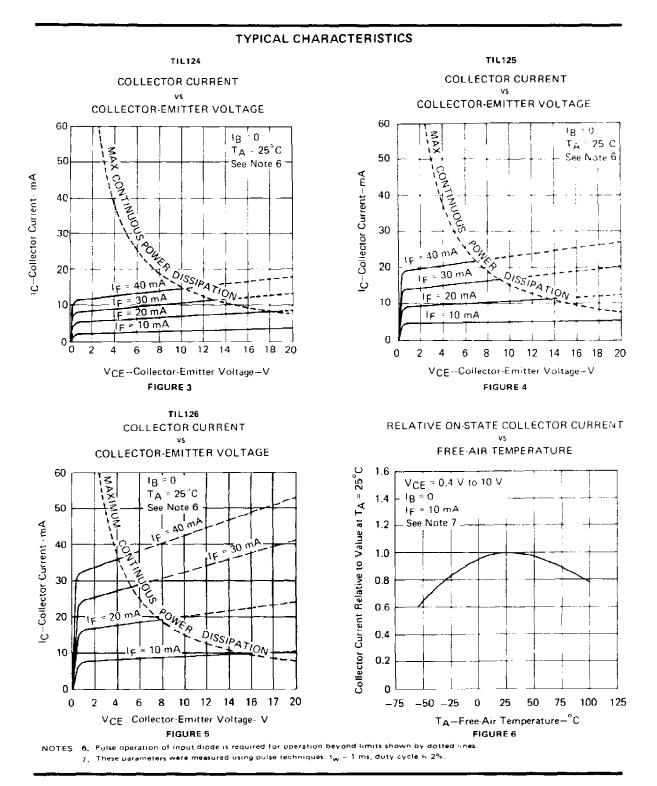


I MEASUREMENT INFORMATION

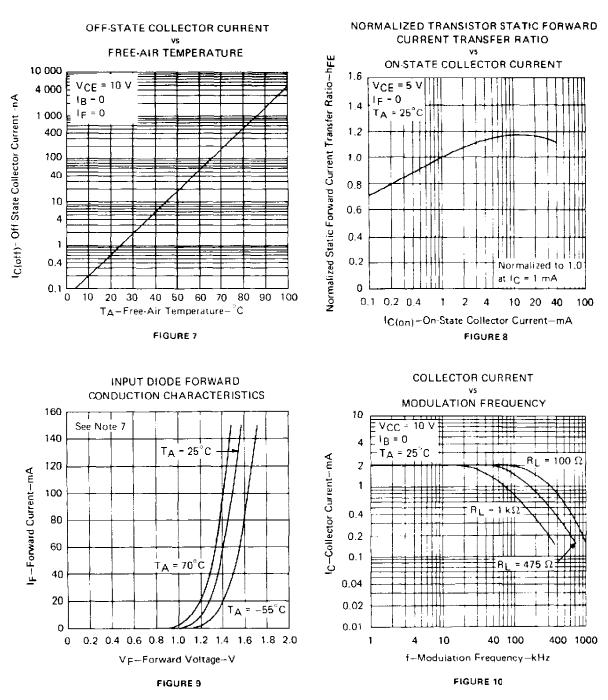
PARAMETER



TIL124, TIL125, TIL126 OPTOCOUPLERS







TYPICAL CHARACTERISTICS

NOTE 7: These parameters were measured using pulse techniques, t_{vv} = 1 ms, duty cycle \leqslant 2%.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TIL124	OBSOLETE	PDIP	Ν	6	TBD	Call TI	Call TI
TIL125	OBSOLETE	PDIP	Ν	6	TBD	Call TI	Call TI
TIL126	OBSOLETE	PDIP	Ν	6	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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OBSOLETE: TI has discontinued the production of the device.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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